

Accelerometers in LGA package

Handling, soldering and mounting instruction

HSMI for Accelerometers in LGA package

Document revision	1.8
Document release date	August 2023
Document number	BST-MAS-HS000-08
Sales Part Number(s)	Valid for all Bosch Sensortec accelerometers (in LGA package) in production
Notes	Data and descriptions in this document are subject to change without notice. Product photos and pictures are for illustration purposes only and may differ from the real product appearance. The technical details and legal disclaimer of the respective product data sheet apply.

Table of Contents

- 1 Purpose of this document..... 4
- 2 Package outline..... 4
- 3 Landing pattern..... 4
- 4 Moisture sensitivity level (MSL) 4
- 5 RoHS compliancy / halogen content 4
- 6 Mounting recommendations 5
 - 6.1 Recommendations in detail..... 5
 - 6.2 Recommendation details..... 6
 - 6.2.1 Push-button contacts..... 6
 - 6.2.2 Thermal hot spots on the PCB 6
 - 6.2.3 Redundant PCB anchor points..... 7
 - 6.2.4 Mechanical stress maximum on the PCB 7
 - 6.2.5 Distance to PCB anchor points 8
 - 6.2.6 Vibrating PCB..... 9
 - 6.3 Resin coatings..... 9
- 7 Note on internal package structures 10
- 8 Device marking 10
- 9 Reflow soldering 10
 - 9.1 Recommendation for soldering of sensors in LGA package..... 10
 - 9.2 Classification reflow profiles..... 11
 - 9.3 Multiple reflow soldering cycles 11
- 10 Tape & reel 11
 - 10.1 Tape & reel specification 11
 - 10.2 Orientation within the reel 11

11 Further important mounting, assembly & handling recommendations 12

12 Document history and modification 13

List of figures

Figure 1: Push-button contacts 6

Figure 2: Thermal hot spots on the PCB..... 6

Figure 3: Redundant PCB anchor points 7

Figure 4: Mechanical stress maximum on the PCB..... 8

Figure 5: Distance to PCB anchor points..... 8

Figure 6: Vibrating PCB 9

Figure 7: Resin coatings 9

Figure 8: Recommendation to keep the side of LGA free from solder material 10

Figure 9: Recommendation not to use underfill for LGA packages 11

1 Purpose of this document

This document describes the recommended conditions and parameters to be applied when handling, soldering and mounting Bosch Sensortec acceleration sensors in LGA package to a PCB.

Important:

- To avoid any damages of the sensor and resultant loss of warranty please strictly keep with the instructions described within this document
- It is also strongly recommended to study the sensor data sheet prior to handling the sensor device
- This document is valid Bosch Sensortec triaxial acceleration sensors as specified by their corresponding technical reference codes. In case the technical reference code of your Bosch Sensortec device is not listed on the title page, please contact your Bosch Sensortec representative
- In case you have any other questions, please do not hesitate to contact your Bosch Sensortec representative for further advice

2 Package outline

Please refer to the latest version of the corresponding product datasheet or preliminary datasheet.

3 Landing pattern

Please refer to the latest version of the corresponding product datasheet or preliminary datasheet.

4 Moisture sensitivity level (MSL)

Please refer to the latest version of the corresponding product datasheet or preliminary datasheet.

5 RoHS compliancy / halogen content

Please refer to the latest version of the corresponding product datasheet or preliminary datasheet.

6 Mounting recommendations

MEMS sensors in general are high-precision measurement devices which consist of electronic as well as mechanical silicon structures. Bosch Sensortec MEMS sensor devices are designed for precision, efficiency, and mechanical robustness.

However, to achieve best possible results for your design, the following recommendations should be taken into consideration when mounting the sensor on a printed-circuit board (PCB).

The scenarios described below - given as examples – may lead to a bending of the PCB, which therefore, might influence the performance of the sensor mounted on the PCB.

To evaluate and to optimize the considered placement position of the sensor on the PCB it is recommended to use additional tools during the design in phase, e.g.:

- regarding thermal aspects: infrared camera
- regarding mechanical stress: warpage measurements and/or FEM-simulations

6.1 Recommendations in detail

- It is generally recommended to keep a reasonable distance between the sensor mounting location on the PCB and the critical points described in the following examples. The exact value for a “reasonable distance” depends on many customer-specific variables and must therefore be determined case by case.
- It is not recommended to place the sensor directly under or next to push-button contacts as this can result in mechanical stress.
- It is not recommended to place the sensor in direct vicinity of extremely hot spots regarding temperature (e.g., a μ Controller or a graphic chip) as this can result in heating-up the PCB and consequently also the sensor nearby.
- It is not recommended to place the sensor in direct vicinity of a mechanical stress maximum (e.g., in the centre of a diagonal crossover, refer to 6.2.4). Mechanical stress can lead to bending of the PCB and of the sensor, nearby.
- Do not mount the sensor too closely to a PCB anchor point, where the PCB is attached to a shelf (or similar) as this could also result in mechanical stress. To reduce potential mechanical stress, minimize redundant anchor points and/or loosen respective screws (refer to 6.2.3).
- After reflow soldering it is generally recommended to wait for min. 8h before performing any inline calibration to reduce the impact of relaxation effects of the PCB.
- It is not recommended to mount the sensor in areas where resonant amplitudes (vibrations) of the PCB are likely or to be expected.
- Please avoid partial coverage of the sensor by any kind of (epoxy) resin, as this can possibly result in mechanical stress.
- Avoid mounting (and operation) of the sensor in the vicinity of strong magnetic, strong electric and/or strong infrared radiation fields (IR).
- Avoid electrostatic charging of the sensor and of the device wherein the sensor is mounted.

In case you have any questions regarding the mounting of the sensor on your PCB, or with regard to evaluate and/or to optimize the considered placement position of the sensor on your PCB, do not hesitate to contact us.

If the above-mentioned recommendations cannot be realized appropriately, a specific in-line offset-calibration after placement of the device onto your PCB might help to minimize potentially remaining effects.

6.2 Recommendation details

6.2.1 Push-button contacts

Keep a reasonable distance to push-button contacts, when placing the sensor device. Do not position the sensor directly beneath a push-button contact.

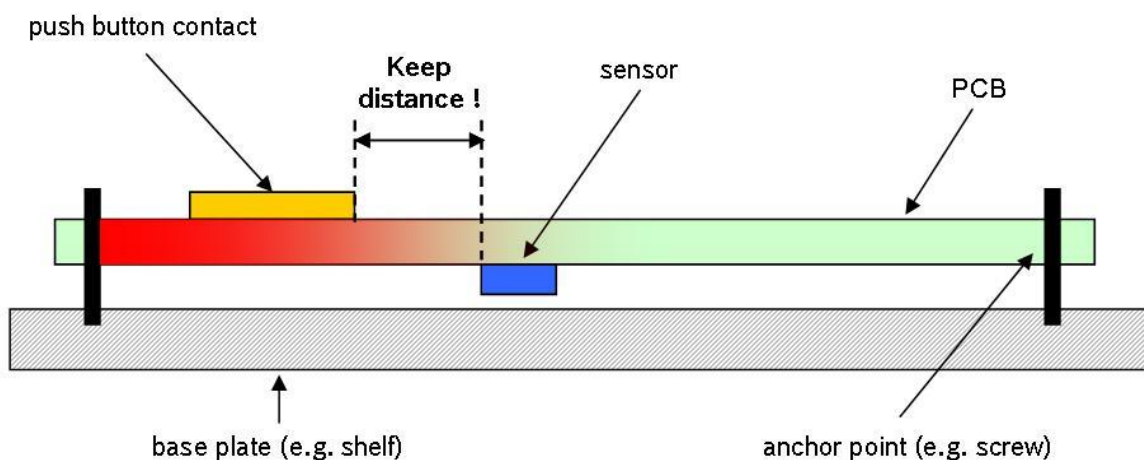


Figure 1: Push-button contacts

6.2.2 Thermal hot spots on the PCB

Keep a reasonable distance from any thermal hot spots, when placing the sensor device. Hot spots can for example be other integrated circuits with high power consumption.

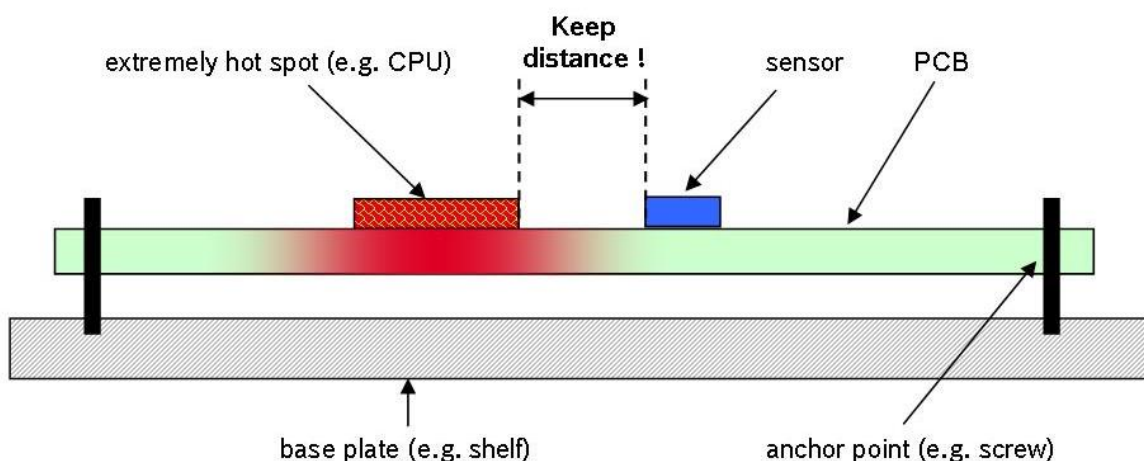


Figure 2: Thermal hot spots on the PCB

6.2.3 Redundant PCB anchor points

It is recommended to unscrew or remove any redundant PCB anchor points. In theory, an ideal flat plane is determined by 3 anchor points, exclusively. Any further anchor point will over-determine the ideal flat plane criteria. If these redundant anchor points are out of plane position (which means not 100% exact in plane position) the ideal flat criteria is infringed, resulting in mechanical stress.

The below given figure describes an expected stress maximum in the centre of the diagonal crossover, assuming that the 4 anchor points are not 100% exact in plane (over-determined ideal flat plane criteria). Unscrewing or removing one of the redundant anchor points can minimize mechanical stress, significantly.

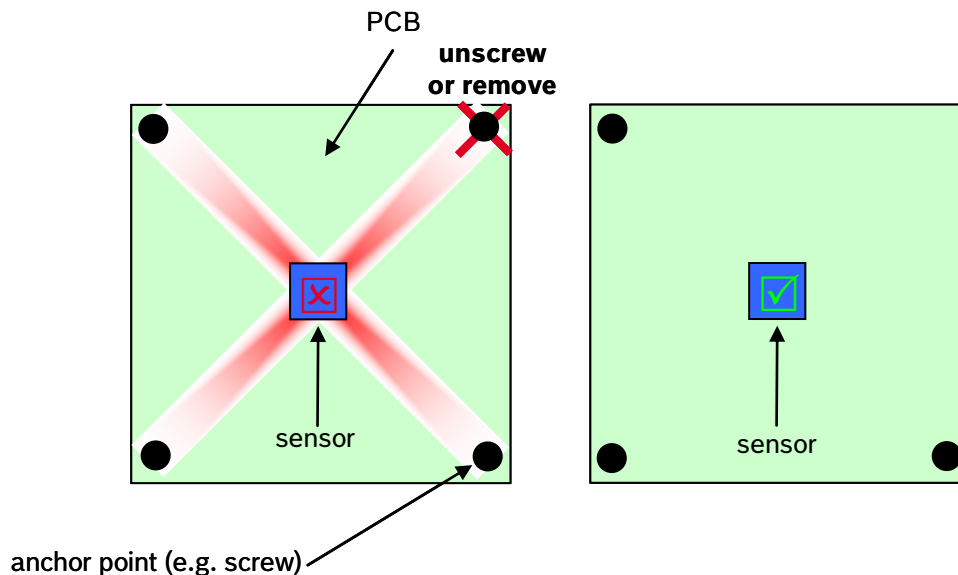


Figure 3: Redundant PCB anchor points

6.2.4 Mechanical stress maximum on the PCB

It is recommended to keep a reasonable distance from any mechanical stress maximum, when placing the sensor device. Mechanical stress can be induced for example by redundant anchor points, as described in 6.2.3.

The below given example will show a stress maximum in the centre of the diagonal crossover of the 4 anchor points. It is good manufacturing practice to always avoid or reduce the mechanical stress by optimizing the PCB design first, then to place the sensor in an appropriate low stress area.

Best practice is to place MEMS components on the PCB in locations where the stress value is not exceeding 500 μ strain.

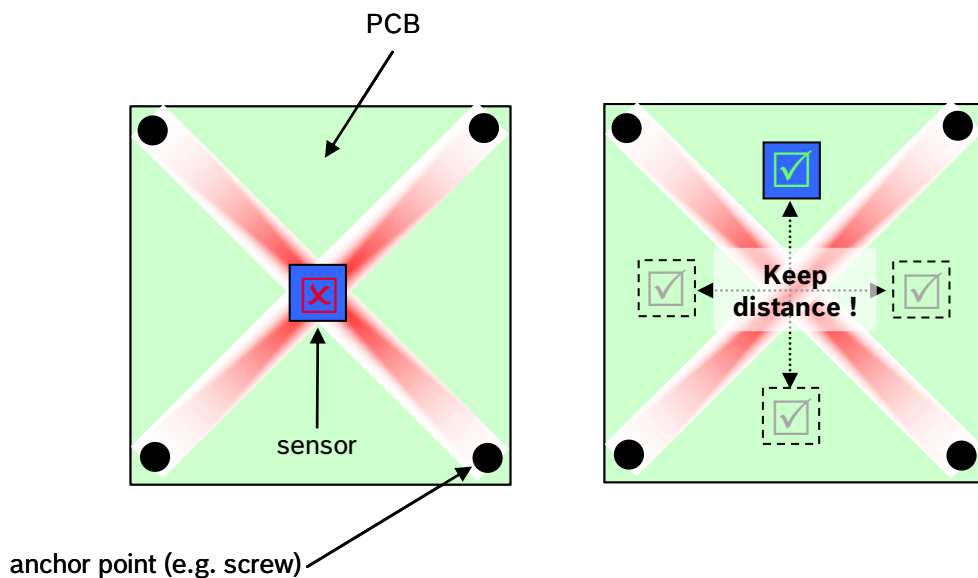


Figure 4: Mechanical stress maximum on the PCB

6.2.5 Distance to PCB anchor points

Please keep a reasonable distance from any anchor points, where the PCB is fixed at a base plate (e.g., like a shelf or similar), when placing the sensor device.

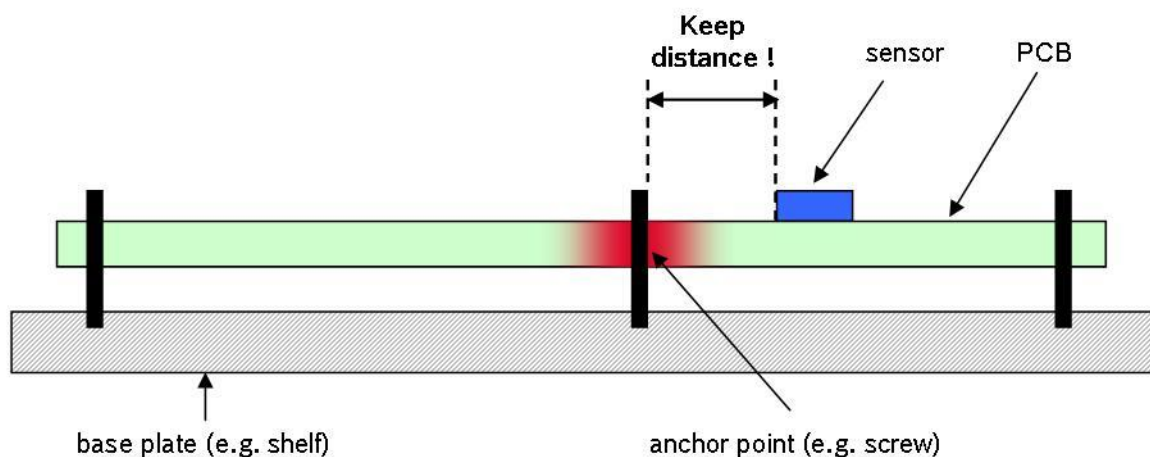


Figure 5: Distance to PCB anchor points

6.2.6 Vibrating PCB

Do not place the sensor in areas where resonant amplitudes (vibrations) of the PCB are likely to occur or to be expected.

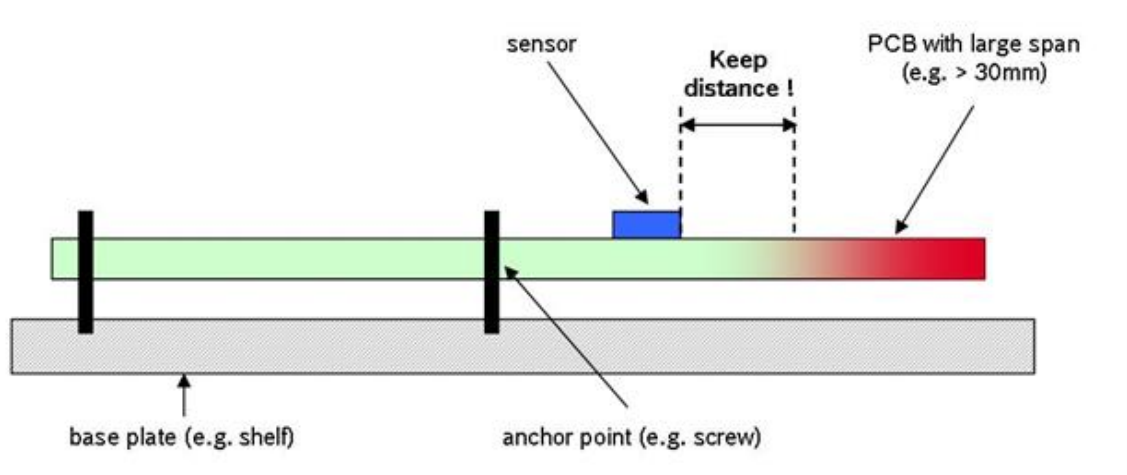


Figure 6: Vibrating PCB

6.3 Resin coatings

Please avoid partial covering of the sensor with any protective material like for example epoxy resin.

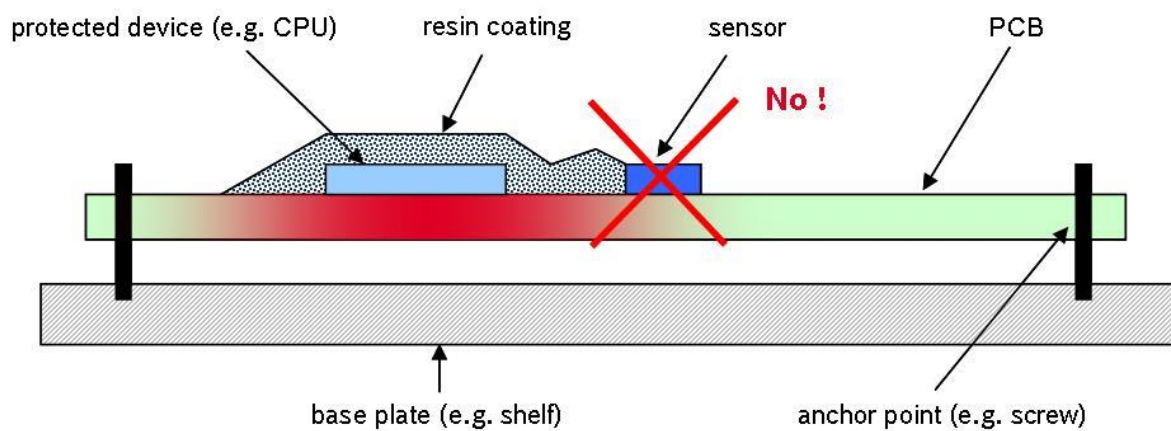


Figure 7: Resin coatings

As shown in the above figure, please take care that the sensor (if at all) is not only partially covered and also not in contact with any (epoxy) resin material leading to an un-symmetric stress distribution over the sensor package.

7 Note on internal package structures

Within the scope of Bosch Sensortec's ambition to improve its products and secure the product supply while in mass production, Bosch Sensortec qualifies additional sources for the LGA package of its sensors.

While Bosch Sensortec took care that all technical package parameters as described above are 100% identical for both sources, there can be differences in the chemical analysis and internal structural between the different package sources.

However, as secured by the extensive product qualification processes at Bosch Sensortec, this has no impact on the usage or the quality of the sensor.

8 Device marking

Please refer to the latest version of the corresponding product data sheet or preliminary data sheet.

9 Reflow soldering

9.1 Recommendation for soldering of sensors in LGA package

Please ensure that the edges of the LGA substrate of the sensor are free of solder material. It is not allowed to allow solder material forming a high meniscus covering the edge of the LGA substrate (compare figure below) since metal traces of the internal LGA substrate wiring are exposed.

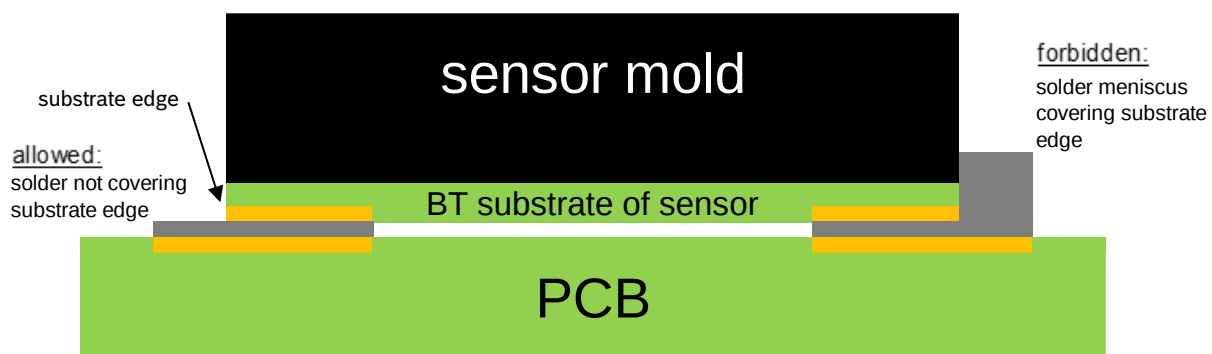


Figure 8: Recommendation to keep the side of LGA free from solder material

Using copper underfill for the LGA package is forbidden, compare figure below.

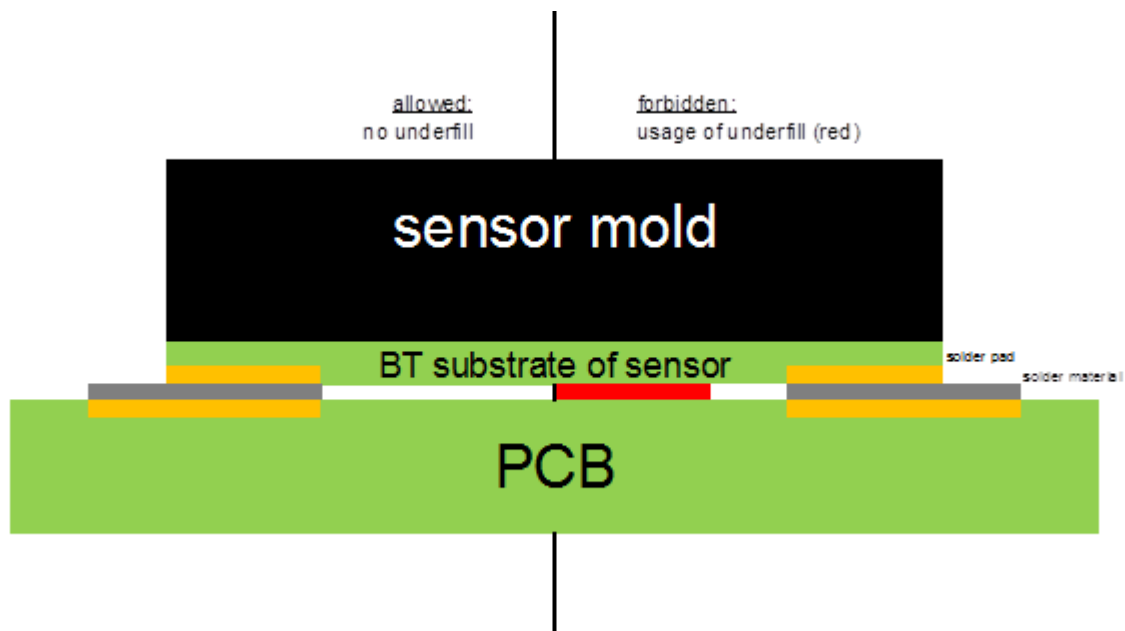


Figure 9: Recommendation not to use underfill for LGA packages

9.2 Classification reflow profiles

The sensor fulfils the JEDEC and lead-free soldering requirements described in chapter 4, i.e. reflow soldering (after MSL1 pre-treatment) with a peak temperature T_p up to 260°C.

9.3 Multiple reflow soldering cycles

The product can withstand in total up to 3 reflow soldering cycles.

This could be a situation where a PCB is mounted with devices from both sides (i.e., 2 reflow cycles necessary) and where in the next step an additional re-work cycle could be required (1 reflow).

10 Tape & reel

10.1 Tape & reel specification

Please refer to the latest version of the corresponding product data sheet or preliminary data sheet.

10.2 Orientation within the reel

Please refer to the latest version of the corresponding product data sheet or preliminary data sheet.

11 Further important mounting, assembly & handling recommendations

Bosch Sensortec's accelerometers are designed to sense acceleration with high accuracy even at low amplitudes and contain highly sensitive structures inside the sensor element. The MEMS sensor can tolerate mechanical shocks up to several thousand g's. However, these limits might be exceeded in conditions with extreme shock loads such as e.g., hammer blow on or next to the sensor, dropping of the sensor onto hard surfaces etc.

We strongly recommend avoiding any g-forces beyond the limits specified in the data sheet during transport, handling and mounting of the sensors in a defined and qualified installation process.

The accelerometers have built-in protections against high electrostatic discharges or electric fields (2kV HBM); however, anti-static precautions should be taken as for any other CMOS component.

Unless otherwise specified, proper operation can only occur when all terminal voltages are kept within the supply voltage range. Unused inputs must always be connected to a defined logic voltage level.

12 Document history and modification

Rev. No	Chapter	Description of modification/changes	Date
1.0		Document creation	21 June 2011
1.1		Added various technical reference codes	05 September 2011
1.2		Added various technical reference codes	27 October 2012
1.3		Added various technical reference codes	08 July 2013
	8	Update	
1.4		Added various technical reference codes	20 August 2015
1.5	5.1	Added waiting time for inline calibration after soldering	19 May 2016
1.6	All	New Layout	September 2019
		Document is valid for all existing BMA sensors	
	4	Update	
	8.1	Update	
	11	Legal disclaimer updated	
1.7	11	Legal disclaimer updated	November 2020
1.8	All	New Template	07 August 2023
	Cover page	Added LGA package	
		Notes adjusted	
	4, 5	Reference to datasheets	
	6.1, 6.2.4	Update	
	[11]	Former chapter 11 Legal disclaimer deleted	

Bosch Sensortec GmbH

Gerhard-Kindler-Straße 9
72770 Reutlingen / Germany

contact@bosch-sensortec.com
www.bosch-sensortec.com

Modifications reserved
Document number: BST-MAS-HS000-08